

June 2014

FQA28N15

N-Channel QFET® MOSFET

150 V, 33 A, 90 mΩ

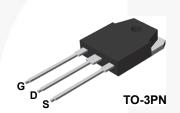
Description

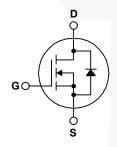
This N-Channel enhancement mode power MOSFET is • 33 A, 150 V, $R_{DS(on)}$ = 90 m Ω (Max.) @ V_{GS} = 10 V, produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state • Low Gate Charge (Typ. 220 nC) resistance, and to provide superior switching performance and • Low Crss (Typ. 110 pF) high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor • 100% Avalanche Tested control, and variable switching power applications.

Features

- $I_D = 16.5 A$

- 175°C Maximum Junction Temperature Rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQA28N15	Unit	
V_{DSS}	Drain-Source Voltage		150	V	
I _D	Drain Current - Continuous (T _C = 25°C)		33	Α	
	- Continuous (T _C = 100°C)		23.3	А	
I _{DM}	Drain Current - Pulsed	Note 1)	132	А	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		300	mJ	
I _{AR}	Avalanche Current (Note 1)		33	Α	
E _{AR}	Repetitive Avalanche Energy (Note 1)		22.7	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		5.5	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		227	W	
	- Derate above 25°C		1.52	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C	
T _L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C	

Thermal Characteristics

Symbol	Parameter	FQA28N15	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.66	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA28N15	FQA28N15	TO-3PN	Tube	N/A	N/A	30 units

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$				V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.17		V/°C
I _{DSS}	Zana Oata Valtana Basin Ourset	V _{DS} = 150 V, V _{GS} = 0 V			1	μΑ
Zero Gate Voltage Drain Current	Zero Gate Voltage Drain Current	V _{DS} = 120 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 16.5 A		0.067	0.09	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 16.5 A		20		S
Dynam	ic Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		1250	1600	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		260	340	pF
C _{rss}	Reverse Transfer Capacitance			50	65	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 75 V, I _D = 28 A,		17	45	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		180	370	ns
t _{d(off)}	Turn-Off Delay Time	- 1.6 2022		100	210	ns
t _f	Turn-Off Fall Time	(Note 4)		115	240	ns
Qg	Total Gate Charge	V _{DS} = 120 V, I _D = 28 A,		40	52	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		7.9		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		20		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				33	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				132	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 33 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 28 A,		100	/	ns
Q _{rr}	Reverse Recovery Charge	$dI_{\rm F}$ / dt = 100 A/µs		0.4		μС

Notes:1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. L = 0.46 mH, I_{AS} = 33 A, V_{DD} = 25 V, R_{G} = 25 Ω , starting T_{J} = 25°C.
3. $I_{SD} \le 28$ A, di/dt ≤ 300 A/us, $V_{DD} \le BV_{DSS}$, starting T_{J} = 25°C.
4. Essentially independent of operating temperature.

Typical Characteristics

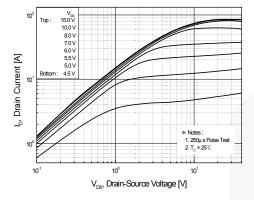


Figure 1. On-Region Characteristics

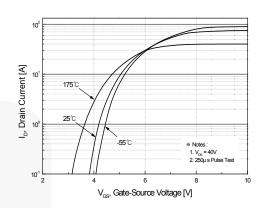


Figure 2. Transfer Characteristics

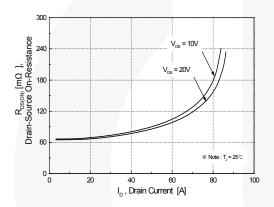


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

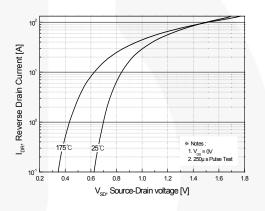


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

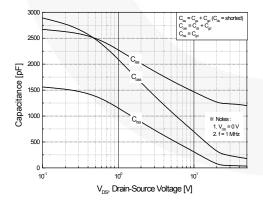


Figure 5. Capacitance Characteristics

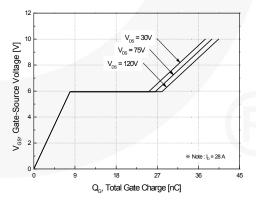


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

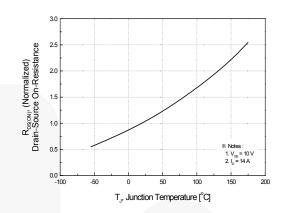
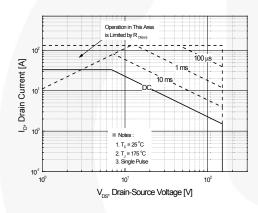


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



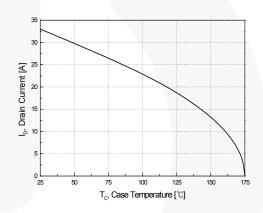


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

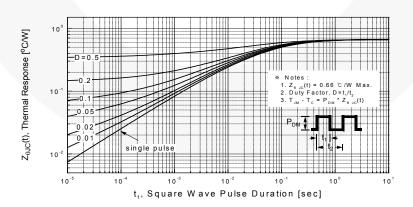


Figure 11. Transient Thermal Response Curve

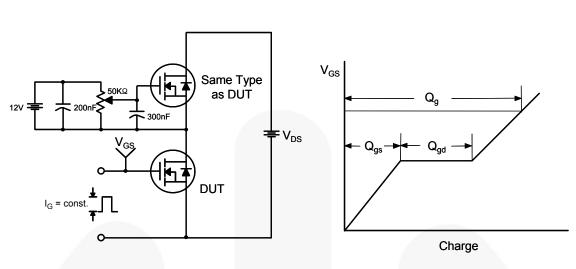


Figure 12. Gate Charge Test Circuit & Waveform

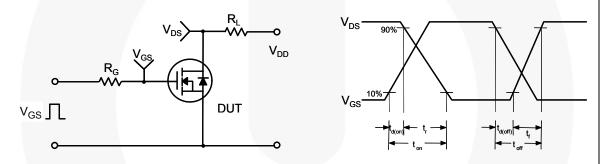


Figure 13. Resistive Switching Test Circuit & Waveforms

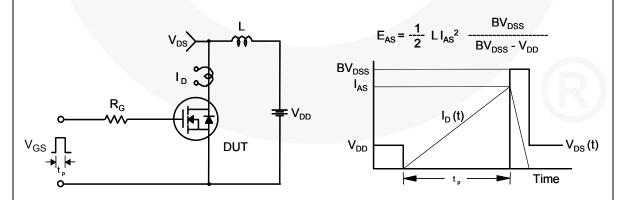
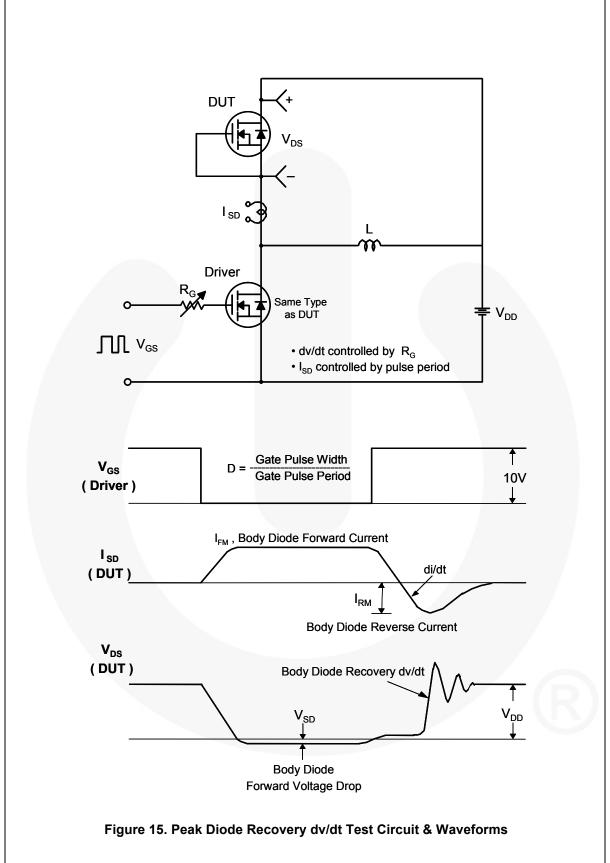
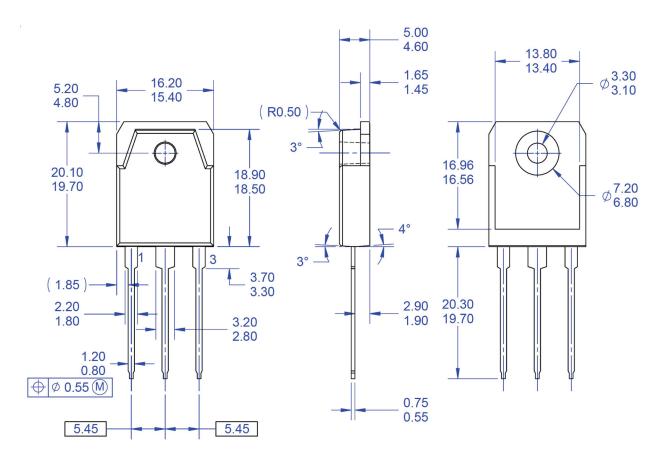
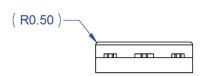


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS. DRAWING FILE NAME: TO3PN03AREV1.
- FAIRCHILD SEMICONDUCTOR.

Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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